

## APPLICATION DATA SHEET

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*Applicant Information:*Inventor 1:

Applicant Authority Type:	Inventor
Citizenship:	JP
Given Name:	Shinji
Family Name:	MAEKAWA
City of Residence:	Iwata, Shizuoka
Country of Residence:	JP
Address-1 of Mailing Address:	3-12-3, Toushin-cyo,
Address-2 of Mailing Address:	
City of Mailing Address:	Iwata-shi, Shizuoka-ken
State of Mailing Address:	
Postal Code of Mailing Address:	438-0039
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	

Inventor 2:

Applicant Authority Type:	Inventor
Citizenship:	JP
Given Name:	Shunpei
Family Name:	YAMAZAKI
City of Residence:	Setagaya, Tokyo
Country of Residence:	JP
Address-1 of Mailing Address:	c/o Semiconductor Energy Laboratory Co., Ltd.
Address-2 of Mailing Address:	398, Hase,
City of Mailing Address:	Atsugi-shi, Kanagawa-ken
State of Mailing Address:	
Postal Code of Mailing Address:	243-0036
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	

Inventor 3:

Applicant Authority Type: Inventor  
Citizenship: JP  
Given Name: Yuko  
Family Name: TACHIMURA  
City of Residence: Atsugi, Kanagawa  
Country of Residence: JP  
Address-1 of Mailing Address: c/o Semiconductor Energy Laboratory Co., Ltd.  
Address-2 of Mailing Address: 398, Hase,  
City of Mailing Address: Atsugi-shi, Kanagawa-ken  
State of Mailing Address:  
Postal Code of Mailing Address: 243-0036  
Country of Mailing Address: JP  
Phone:  
Fax:  
E-mail:

Inventor 4:

Applicant Authority Type: Inventor  
Citizenship: JP  
Given Name: Koji  
Family Name: MURANAKA  
City of Residence: Kumamoto, Kumamoto  
Country of Residence: JP  
Address-1 of Mailing Address: 4-33, Idenakama,  
Address-2 of Mailing Address:  
City of Mailing Address: Kumamoto-shi, Kumamoto-ken  
State of Mailing Address:  
Postal Code of Mailing Address: 862-0963  
Country of Mailing Address: JP  
Phone:  
Fax:  
E-mail:

*Correspondence Information:*

Customer Number: 22204 \*22204\*

*Application Information:*

Title of Invention: METHOD FOR FORMING WIRING, METHOD FOR  
MANUFACTURING THIN FILM TRANSISTOR OR AND  
DROPLET DISCHARGING METHOD

Application Type: regular, utility

Attorney Docket Number: 740756-2947

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Suggested Figure for Publication -

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*Representative Information:*

practitioner(s) at Customer Number:

22204

\*22204\*

as our attorney(s) or agent(s) to prosecute the application identified above, and to  
transact all business in the United States Patent and Trademark Office connected  
therewith.

*Domestic Priority Information:*

This is a National Stage of JP application number PCT/JP2004/016181, filed 2004-10-  
25, now pending.

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*Assignee Information:*Assignee 1:

Organization Name: Semiconductor Energy Laboratory Co., Ltd.

Address-1 of Mailing Address: 398, Hase,

Address-2 of Mailing Address:

City of Mailing Address: Atsugi-shi, Kanagawa-ken

State of Mailing Address:

Postal Code of Mailing Address: 243-0036

Country of Mailing Address: JP

Phone:

Fax:

E-mail: